	Product Series Code	GTXF	Brand	GOTREND
	File Version	GTXF-004-V0	Editor	Teddy
	Established Date	2009.02.09	Description	SMD BALUM
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Features & Application:

- * Common Mode Filter for USB2.0 / IEEE1394
- * Fit for power line & signal line circuit
- * To help you go pass the CE/FCC standard.
- * Mobile Device / Handheld Device / LowProfile Device / Panel...

Part No Example:

GTXF 004 P - 2R0 T
 1 2 3 4 5

1. GTXF : GOTREND Series
2. 004 : BALUN CORE with 6 Pin Base
3. P : Pb free <1000ppm
4. 2R0 : Insertion loss [dB] @ 100MHz = 2.0 Max.
5. T : GOTREND internal code

Insertion loss :

Insertion loss	Specification (A)	Specification (B)
10 MHz	2.5 dB max.	Initial +/- 2.0 dB
100 MHz	2.0 dB max.	Initial +/- 1.5 dB
500 MHz	3.0 dB max.	Initial +/- 1.5 dB
1000 MHz	3.5 dB max.	Initial +/- 2.0 dB

Note :

- * SPEC A is initial value
- * SPEC B is permissible value or changes after environmental test

Test Equipment :

* HP8753E NETWORK ANALYZER

Standard Atmospheric Conditions:

Ambient Temp:20+/-15°C

Relative Humidity:65+/-20%

If there may be any doubt on the result, measurement shall be made within the following limits:

Ambient Temp:25+/-5°C

Relative Humidity:75+/-10%

Operating & Storage Condition:

OPERATING TEMP:-40~+85°C

STORAGE TEMP:-40~+85°C





STORAGE LIFE TIME: 12 MONTH @25°C , RH 65%

Attention & Caution:

Please avoid following matters:

- * Splashing water or salt water
- * Toxic Gas (Hydrogen sulfide, Sulfurous acid, Chlorine, Ammonia)
- * Vibrations or shocks which exceed the specified condition
- * Dew condensates
- * Please be careful for the stress to this product by board flexure or something after the mounting.

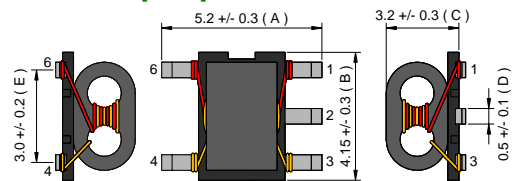
Product Structure

SMD	DIP	Shield	Unshield
			

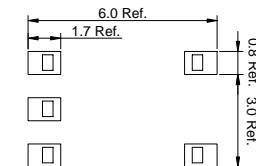
2005 RoHS Compliant - SGS Certified Result

鉛 Pb	鎘 Cd	汞 Hg	六價鉻 Cr+6	溴化聯苯 PBB	溴化聯苯 醚PBDE
<1000ppm	ND	ND	ND	ND	ND

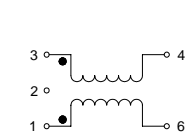
Dimension : [mm]



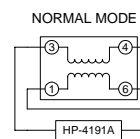
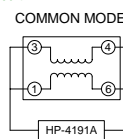
Dimension Layout Recommended



Connection : [Bottom View]



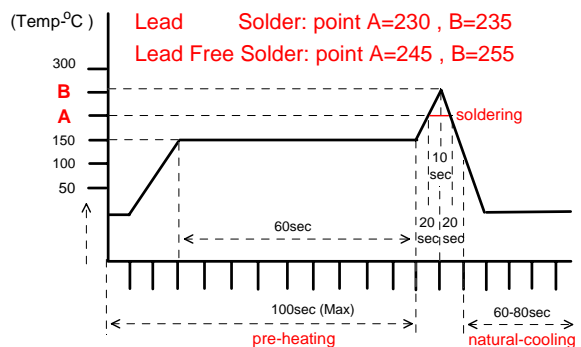
Test Circuit



Electrical :

Item	Standards	Conditions	Test Equipment
Impedance	150 Ohm min.	25 MHz	HP-4191A
	400 Ohm min.	100 MHz	
DCR	120 m Ohm max.	DC Resistance	CH-502A
IDC	0.5 A max.	Rated Current	CH-1320
Withstand Voltage	100 VDC	NO Apparent at 100 VDC for 1 Minute Between	YD-2672
Insulation Resistance	100 M Ohm min.	Over 100 M Ohm at 100 VDC Between Pin-Pin	CH-9052A

Recommand Reflow Curve (TIME:Second)




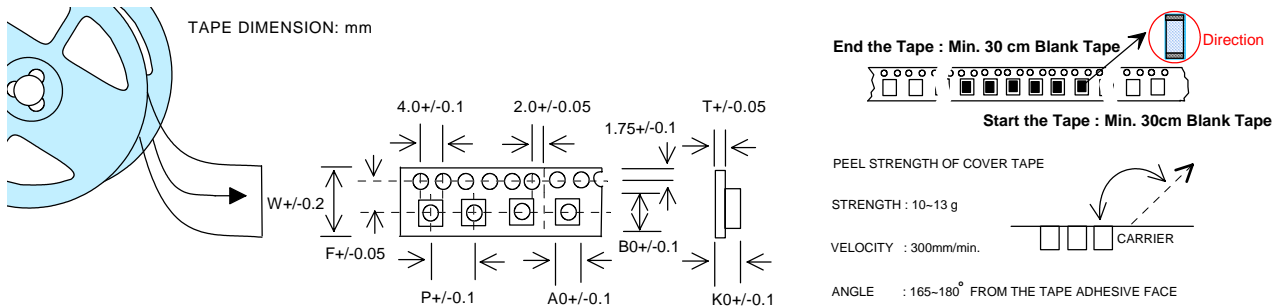
Notice: Iron Soldering: 3 Seconds Max. @260°C



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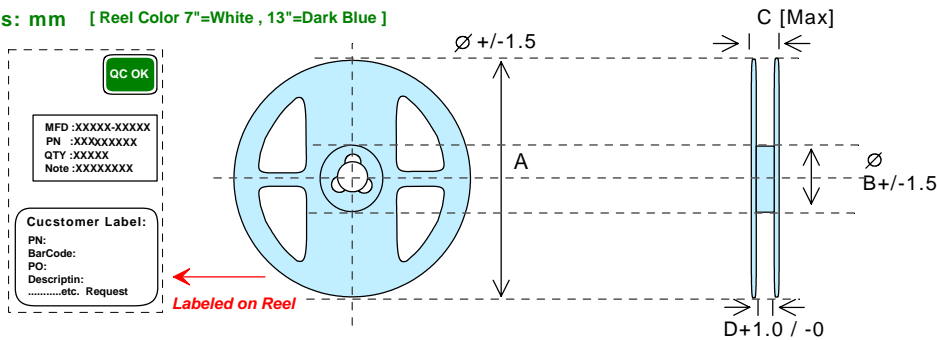
Reliability Test Result :																				
NO	ITEM	TEST CONDITIONS			REMARKS															
1	Thermal Shock (Temperature Cycle) 溫度循環試驗	Temperature:-40 ° C/ +85 ° C kept stabilized for 30 minutes each Cycle: 100 Cycles			Inductance value shall be within ± 10% of the initial value. Q-factor shall be within ± 30% of the initial value. Impedance shall be within ± 20% of the initial value. DCR value shall be within ± 20% of the initial value. NO.1~4 Measurement:After placing for 24 hours (min.) NO.2~3 Applied current(spec): Rated current(maximum value) NO.5 Cycle: 5 cycles															
2	Humidity Resistance 耐濕試驗	Humidity: 90%~ 95% RH Temperature: 40± 2 ° C Test Time: 1000± 12 Hours																		
3	High Temperature 耐熱試驗	Temperature: 85± 2 ° C Humidity: 20% Testing Time: 1000± 12 Hours																		
4	Low Temperature 耐寒試驗	Temperature: -40 ± 2 ° C Time: 1000± 12 Hours																		
5	Temperature and Humidity Cycle 溫/濕度循環試驗	<table border="1"> <thead> <tr> <th>Step</th> <th>Temp</th> <th>Humidity</th> <th>Time</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>25± 2 ° C</td> <td>95~100%RH</td> <td>3.0Hr</td> </tr> <tr> <td>2</td> <td>55± 2 ° C</td> <td>95~96%RH</td> <td>9.5Hr</td> </tr> <tr> <td>3</td> <td>25± 2 ° C</td> <td>95~100%RH</td> <td>9.5Hr</td> </tr> </tbody> </table>	Step	Temp		Humidity	Time	1	25± 2 ° C	95~100%RH	3.0Hr	2	55± 2 ° C	95~96%RH	9.5Hr	3	25± 2 ° C	95~100%RH	9.5Hr	
Step	Temp	Humidity	Time																	
1	25± 2 ° C	95~100%RH	3.0Hr																	
2	55± 2 ° C	95~96%RH	9.5Hr																	
3	25± 2 ° C	95~100%RH	9.5Hr																	
6	Vibration 振動性試驗	Frequency: 10Hz~55Hz Amplitude: 1.5mm Direction: X,Y,Z Time: 2 Hours each																		
7	IR Reflow Soldering 焊錫性試驗	Solder: H63A(eutectic solder) Solder Temp.: 230± 5 ° C Time: 6 minutes Cycles: x 1			Impedance(inductance) shall be within ± 20% of the initial value. DCR value shall be within ± 20% of the initial value.															
8	Soldering Heat Resistance 耐熱 焊性試驗	Preheat: 120 ~ 150 ° C (60 sec) Solder:H63A(eutectic solder) Solder Temp.: 260 ± 5 ° C Flux: Rosin Dip time: 10± 1 seconds			The chip must have no cracks.More than 75% of the terminal electrode must be covered with solder.															
9	Bending Strength 折斷力試驗				The terminal electrode and the ferrite must not be damaged by the forces applied on the test conditions. 3 kg															
10	Flexure Strength 彎曲試驗				No mechanical damage shall be noticed even when the board is bent 2 mm															
11	Terminal Strength 拉力試驗				The terminal electrode and the ferrite must not be damaged by the forces applied on the test conditions. 2.0kg															

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SIZE/μl	A0	B0	F	P	K0	W	T
GTXF	4.40	5.70	5.50	8.00	3.40	12.00	0.40

Reel Dimensions: mm [Reel Color 7"=White , 13"=Dark Blue]



SIZE / mm	A	B	C	D	REEL SIZE	QTY/REEL
GTXF	330	100	18.5	12.5	13"	2.0K

BOX Package: Unit: cm

